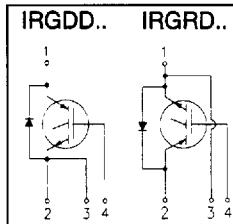


# IRGDDN400K06 IRGRDN400K06

"SINGLE SWITCH" IGBT DOUBLE INT-A-PAK

Low conduction loss IGBT

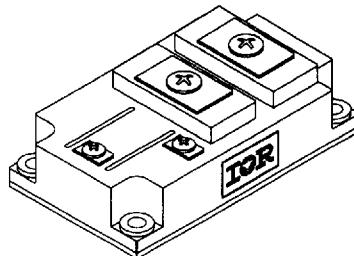
- Rugged Design
- Simple gate-drive
- Switching-Loss Rating includes all "tail" losses
- Short circuit rated



$V_{CE} = 600V$   
 $I_C = 400A$   
 $V_{CE(ON)} < 2.7V$   
 $t_{sc} > 10\mu s$

## Description

IR's advanced IGBT technology is the key to this line of DOUBLE INT-A-PAK Power Modules. The efficient geometry and unique processing of the IGBT allow higher current densities than comparable bipolar power module transistors, while at the same time requiring the simpler gate-drive of the familiar power MOSFET. This superior technology has now been coupled to state of the art assembly techniques to produce a higher current module that is highly suited to power applications such as motor drives, uninterruptible power supplies, welding and power factor correction.



DOUBLE INT-A-PAK case

## Absolute Maximum Ratings

Parameter	Description	Value	Units
$V_{CES}$	Continuous collector to emitter voltage	600	V
$I_C @ T_C = 25^\circ C$	Maximum Continuous collector current	520	
$I_C @ T_C = 85^\circ C$	Maximum Continuous collector current	280	
$I_C @ T_C = 100^\circ C$	Maximum Continuous collector current	200	A
$I_{LM}$	Peak switching current	800	
$I_{FM}$	Peak diode forward current (1)	800	
$V_{GE}$	Gate to emitter voltage	$\pm 20$	V
$V_{ISOL}$	RMS isolation voltage, any terminal to case, $t = 1 \text{ min}$	2500	
$P_D @ T_C = 25^\circ C$	Power dissipation	1984	
$T_J$	Operating junction temperature range	-40 to 150	$^\circ C$
$T_{STG}$	Storage temperature range	-40 to 125	

(1) Duration limited by max junction temperature

Target Data

# IRGDDN400K06 IRGRDN400K06

Target Data



## Electrical Characteristics - $T_J = 25^\circ\text{C}$ , unless otherwise stated

Parameter	Description	Min	Typ	Max	Units	Test Conditions
$\text{BV}_{\text{CES}}$	Collector-to-emitter breakdown voltage	600	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 6\text{mA}$
$V_{\text{CE}}(\text{ON})$	Collector-to-emitter voltage	—	—	2.7		$V_{\text{GE}} = 15\text{V}, I_C = 400\text{A}$
		—	2.7	—		$V_{\text{GE}} = 15\text{V}, I_C = 400\text{A}, T_J = 125^\circ\text{C}$
$V_{\text{FM}}$	Diode forward voltage - maximum	—	1.8	2.0	V	$I_F = 400\text{A}, V_{\text{GE}} = 0\text{V}$
		—	1.8	—		$I_F = 400\text{A}, V_{\text{GE}} = 0\text{V}, T_J = 125^\circ\text{C}$
$V_{\text{GEth}}$	Gate threshold voltage	3.0	—	5.5	mA	$I_C = 3\text{mA}$
$\text{DV}_{\text{GEth}}$	Threshold voltage temperature coefficient	—	-11	—		$V_{\text{CE}} = V_{\text{GE}}, I_C = 3\text{mA}$
$g_{\text{fe}}$	Forward transconductance	204	—	348		$V_{\text{CE}} = 25\text{V}, I_C = 300\text{A}$
$I_{\text{CES}}$	Collector-to-emitter leakage current	—	—	6		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}$
		—	—	60		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}, T_J = 125^\circ\text{C}$
$I_{\text{GES}}$	Gate-to-emitter leakage current	—	—	$\pm 6$	$\mu\text{A}$	$V_{\text{GE}} = \pm 20\text{V}$

## Dynamic Characteristics - $T_J = 125^\circ\text{C}$

Parameter	Description	Min	Typ	Max	Units	Test Conditions
$E_{\text{on}}$ $E_{\text{off}}$ (1) $E_{\text{ts}}$ (1)	Turn-on switching energy	—	0.04	—	mJ/A	$R_G = 15\Omega, V_{\text{CC}} = 300\text{V}$
	Turn-off switching energy	—	0.06	—		$I_C = 400\text{A}, L_S = 100\text{nH}$
	Total switching energy	—	—	0.15		$V_{\text{GE}} = \pm 15\text{V}$
$t_{\text{d(on)}}$ $t_r$	Turn-on delay time	—	300	—	ns	$R_G = 15\Omega, V_{\text{CC}} = 300\text{V}$
	Rise time	—	900	—		$I_C = 400\text{A}$
$t_{\text{d(off)}}$ $t_f$	Turn-off delay time	—	700	—		$V_{\text{GE}} = \pm 15\text{V}$
	Fall time	—	120	—		Resistive Load, $T_J = 25^\circ\text{C}$
$I_{\text{rr}}$ $t_{\text{rr}}$ $Q_{\text{rr}}$	Diode peak recovery current	—	110	—	A	$R_G = 15\Omega, V_{\text{CC}} = 300\text{V}$
	Diode recovery time	—	110	—	ns	$I_C = 400\text{A}$
	Diode recovery charge	—	6	—	$\mu\text{C}$	$V_{\text{GE}} = \pm 15\text{V}$
$Q_{\text{ge}}$ $Q_{\text{gc}}$ $Q_g$	Gate-to-emitter charge (turn-on)	156	—	252	nC	$V_{\text{CC}} = 480\text{V}$
	Gate-to-collector charge (turn-on)	420	—	840		$I_C = 324\text{A}$
	Total gate charge (turn-on)	900	—	1680		$V_{\text{GE}} = 15\text{V}$
$C_{\text{ies}}$ $C_{\text{oes}}$ $C_{\text{res}}$	Input capacitance	—	34800	—	pF	$V_{\text{GE}} = 0\text{V}$
	Output capacitance	—	3960	—		$V_{\text{CC}} = 30\text{V}$
	Reverse transfer capacitance	—	480	—		f = 1MHz
$t_{\text{sc}}$	Short circuit withstand time	10	—	—	$\mu\text{s}$	$V_{\text{CC}} = 360\text{V}, V_{\text{GE}} = \pm 15\text{V}$ Min. $R_G = 15\Omega, V_{\text{CEP}} = 500\text{V}$

(1) Includes tail losses

## Thermal and Mechanical Characteristics

Parameter	Description	Typ	Max	Units
$R_{\text{thJC}}$ (IGBT)	Thermal resistance, junction to case, each IGBT	—	0.063	°C/W
$R_{\text{thJC}}$ (Diode)	Thermal resistance, junction to case, each diode	—	0.095	
$R_{\text{thCS}}$ (Module)	Thermal resistance, case to sink	0.023	0.050	
Wt	Weight of module	242	—	g

Refer to Section D - page D-18 for Package Outline 13 - Double INT-A-Pak Single Switch